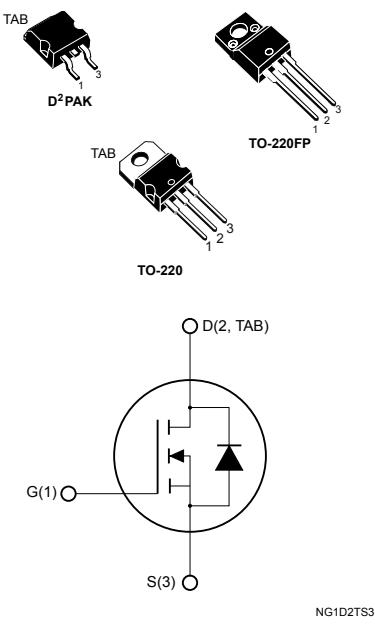


N-channel 500 V, 300 mΩ typ., 12 A MDmesh Power MOSFETs  
in a D<sup>2</sup>PAK, TO-220 and TO-220FP packages



## Features

Order codes	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STB12NM50T4	500 V	350 mΩ	12 A
STP12NM50			
STP12NM50FP			

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

## Applications

- Switching applications

## Description

These N-channel Power MOSFETs are developed using STMicroelectronics' revolutionary MDmesh technology, which associates the multiple drain process with the company's PowerMESH horizontal layout. These devices offer extremely low on-resistance, high dv/dt and excellent avalanche characteristics. Utilizing ST's proprietary strip technique, these Power MOSFETs boast an overall dynamic performance which is superior to similar products on the market.



### Product status link

<a href="#">STB12NM50T4</a>
<a href="#">STP12NM50</a>
<a href="#">STP12NM50FP</a>

## 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		D <sup>2</sup> PAK, TO-220	TO-220FP	
V <sub>GS</sub>	Gate-source voltage	±30		V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	12	12 <sup>(1)</sup>	A
	Drain current (continuous) at T <sub>C</sub> = 100 °C	7.5	7.5 <sup>(1)</sup>	
I <sub>DM</sub> <sup>(2)</sup>	Drain current pulsed	48	48 <sup>(1)</sup>	A
P <sub>TOT</sub>	Total power dissipation at T <sub>C</sub> = 25 °C	160	35	W
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s, T <sub>C</sub> = 25 °C)			2.5 kV
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	15		V/ns
T <sub>J</sub>	Operating junction temperature range	-65 to 150		°C
T <sub>stg</sub>	Storage temperature range			°C

1. Limited by maximum junction temperature.
2. Pulse width limited by safe operating area.
3. I<sub>SD</sub> ≤ 12 A, di/dt ≤ 400 A/μs, V<sub>DD</sub> = 80% V<sub>(BR)DSS</sub>.

**Table 2. Thermal data**

Symbol	Parameter	Value			Unit
		D <sup>2</sup> PAK	TO-220	TO-220FP	
R <sub>thj-case</sub>	Thermal resistance junction-case	2.78	3.57	3.57	°C/W
R <sub>thj-a</sub>	Thermal resistance junction-ambient	62.5			°C/W
R <sub>thj-pcb</sub> <sup>(1)</sup>	Thermal resistance junction-pcb	35			°C/W

1. When mounted on an 1-inch<sup>2</sup> FR-4, 2 Oz copper board.

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
I <sub>AS</sub>	Avalanche current, repetitive or not repetitive (pulse width limited by T <sub>J</sub> max)	6	A
E <sub>AS</sub>	Single-pulse avalanche energy (starting T <sub>J</sub> = 25 °C, I <sub>D</sub> = I <sub>AS</sub> , V <sub>DD</sub> = 50 V)	400	mJ

## 2 Electrical characteristics

( $T_C = 25^\circ\text{C}$  unless otherwise specified)

**Table 4. Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	500			V
$I_{\text{DSS}}$	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 500 \text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0 \text{ V}, V_{DS} = 500 \text{ V}, T_C = 125^\circ\text{C}$ (1)			10	
$I_{\text{GSS}}$	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 30 \text{ V}$			$\pm 100$	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 50 \mu\text{A}$	3	4	5	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$		300	350	$\text{m}\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	1000	-	pF
$C_{oss}$	Output capacitance		-	250	-	pF
$C_{rss}$	Reverse transfer capacitance		-	20	-	pF
$C_{oss \text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0 \text{ to } 400 \text{ V}, V_{GS} = 0 \text{ V}$	-	90	-	pF
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 250 \text{ V}, I_D = 6 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	20	-	ns
$t_r$	Rise Time		-	10	-	ns
$Q_g$	Total gate charge	$V_{DD} = 400 \text{ V}, I_D = 12 \text{ A}, V_{GS} = 0 \text{ to } 10 \text{ V}$ (see Figure 14. Test circuit for gate charge behavior)	-	28	-	nC
$Q_{gs}$	Gate-source charge		-	8	-	nC
$Q_{gd}$	Gate-drain charge		-	16	-	nC
$R_g$	Gate input resistance	$f = 1 \text{ MHz}, \text{gate DC Bias} = 0, \text{test signal level} = 20 \text{ mV, open drain}$	-	1.6	-	$\Omega$

1.  $C_{oss \text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Source-drain diode**

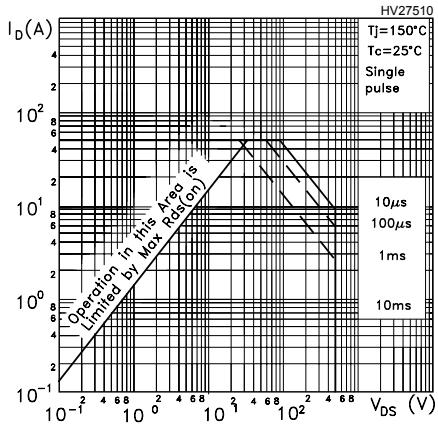
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		12	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		48	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0 \text{ V}$ , $I_{SD} = 12 \text{ A}$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 12 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ ,	-	270		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 100 \text{ V}$	-	2.23		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	16.5		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 12 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ ,	-	340		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 100 \text{ V}$ , $T_J = 150 \text{ }^\circ\text{C}$	-	3		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	18		A

1. Pulse width is limited by safe operating area.

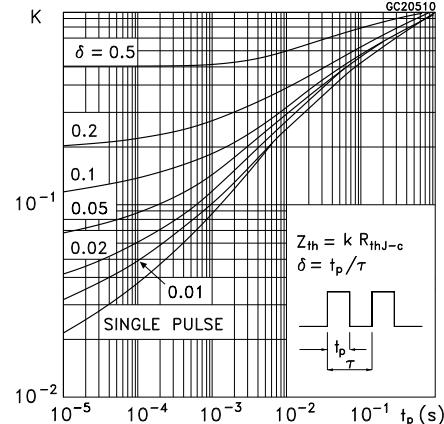
2. Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

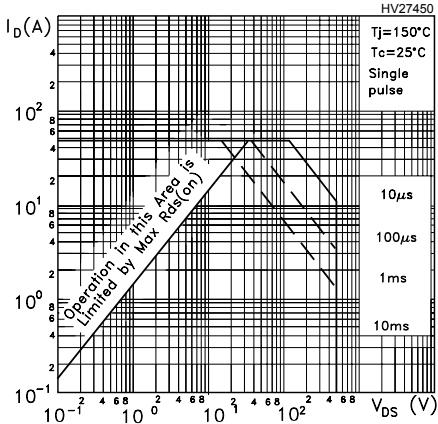
**Figure 1. Safe operating area for D<sup>2</sup>PAK and TO-220**



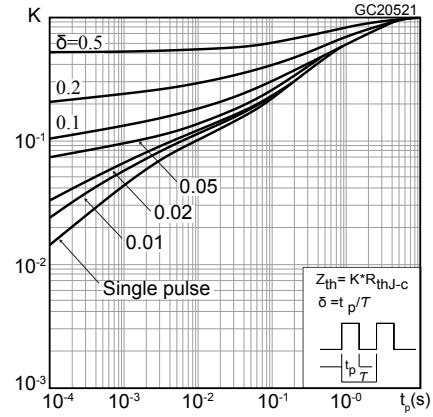
**Figure 2. Thermal impedance for D<sup>2</sup>PAK and TO-220**



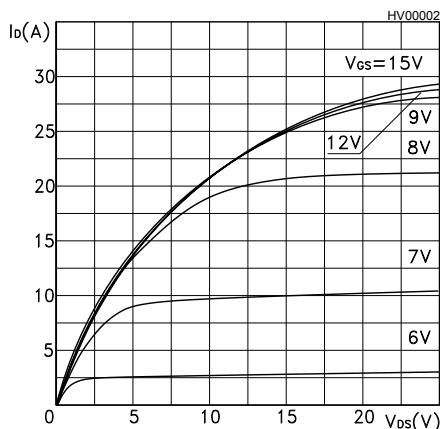
**Figure 3. Safe operating area for TO-220FP**



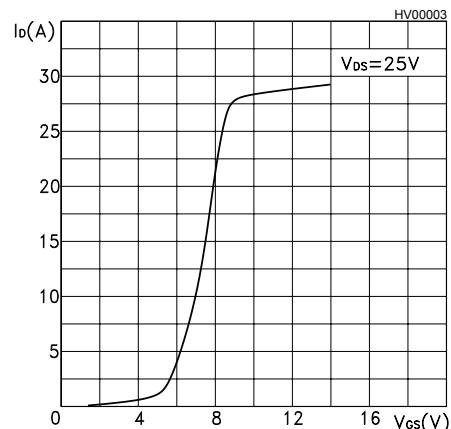
**Figure 4. Thermal impedance for TO-220FP**

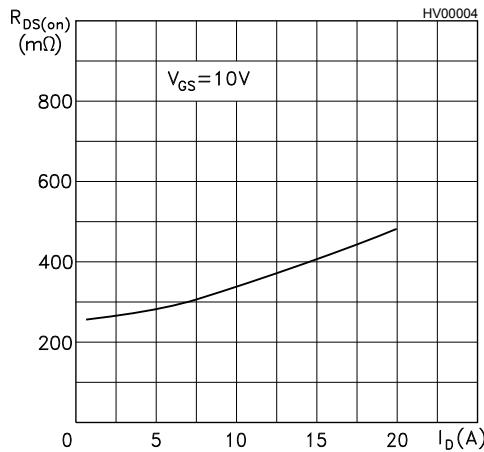
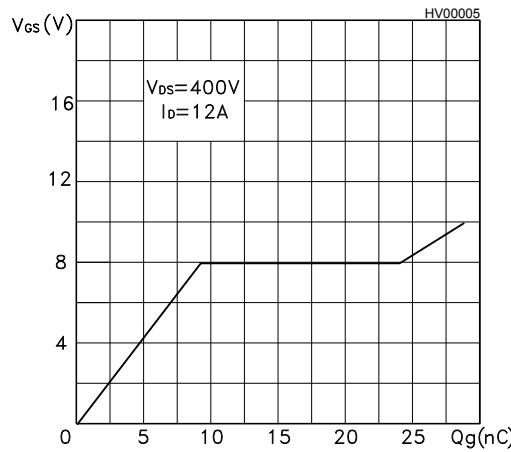
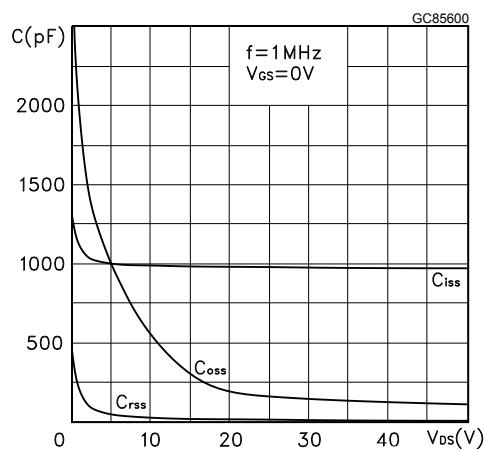
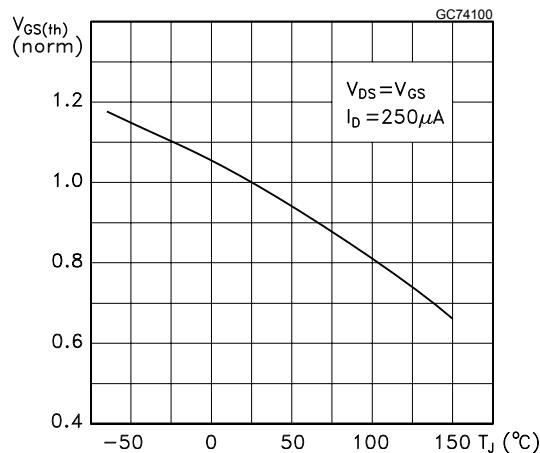
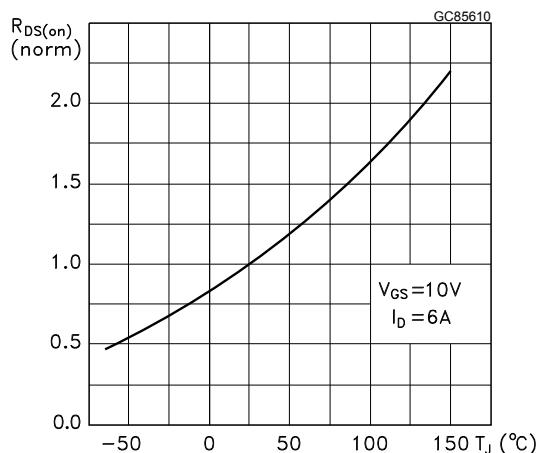
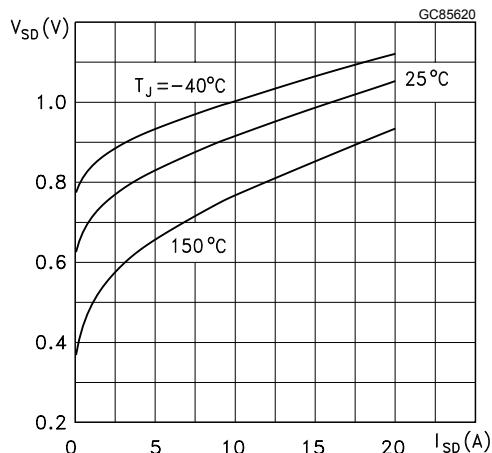


**Figure 5. Output characteristics**



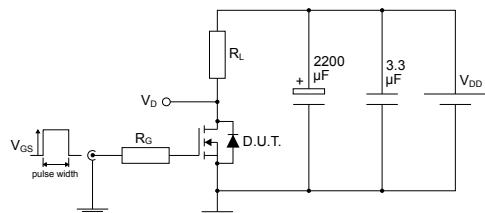
**Figure 6. Transfer characteristics**



**Figure 7. Static drain-source on-resistance**

**Figure 8. Gate charge vs gate-source voltage**

**Figure 9. Capacitance variations**

**Figure 10. Normalized gate threshold voltage vs temperature**

**Figure 11. Normalized on resistance vs temperature**

**Figure 12. Source-drain diode forward characteristics**


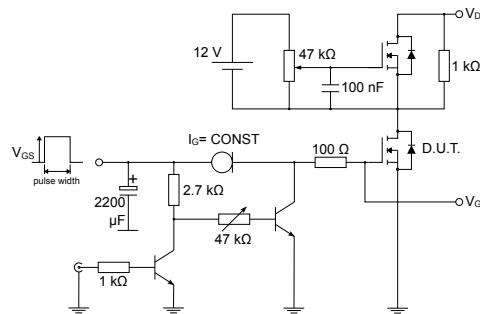
### 3 Test circuits

**Figure 13. Test circuit for resistive load switching times**



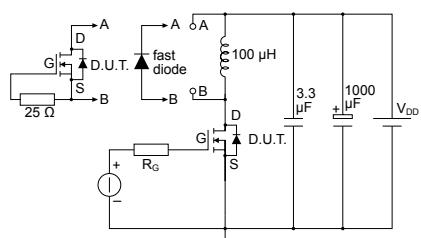
AM01468v1

**Figure 14. Test circuit for gate charge behavior**



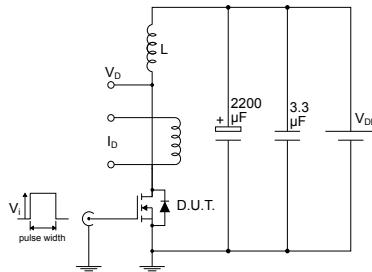
AM01469v1

**Figure 15. Test circuit for inductive load switching and diode recovery times**



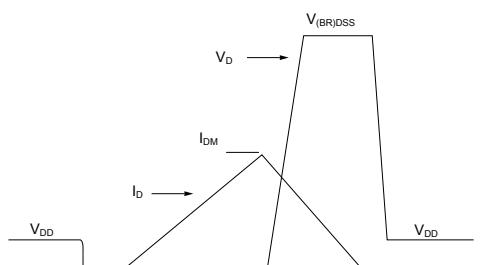
AM01470v1

**Figure 16. Unclamped inductive load test circuit**



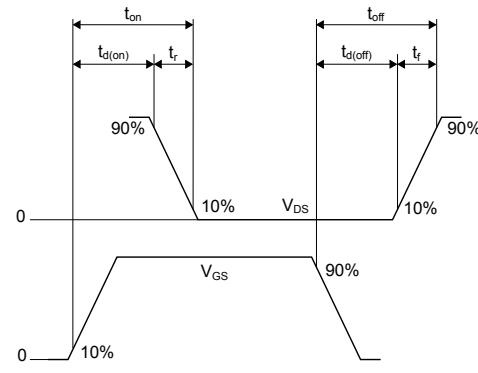
AM01471v1

**Figure 17. Unclamped inductive waveform**



AM01472v1

**Figure 18. Switching time waveform**



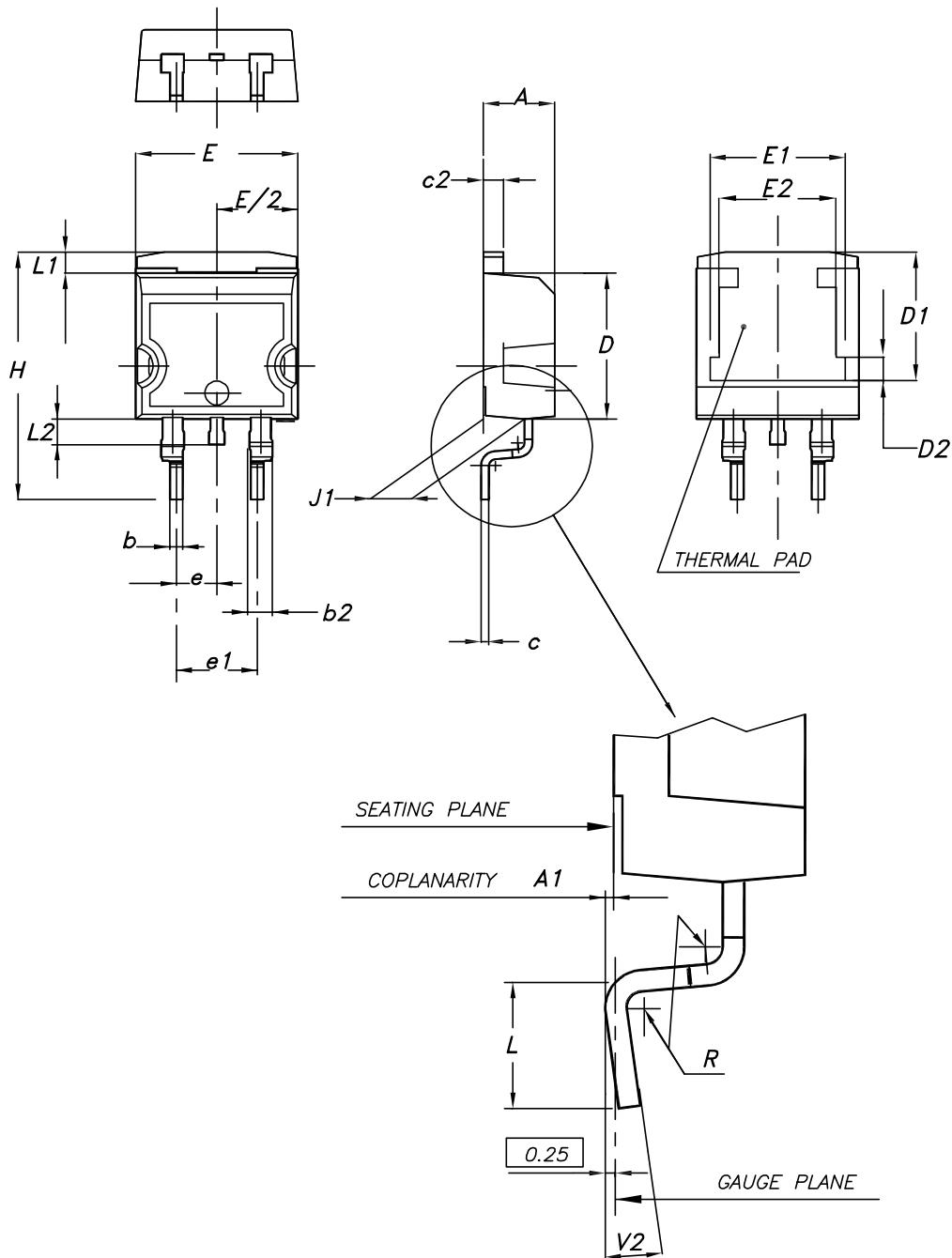
AM01473v1

## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 D<sup>2</sup>PAK (TO-263) type A package information

Figure 19. D<sup>2</sup>PAK (TO-263) type A package outline

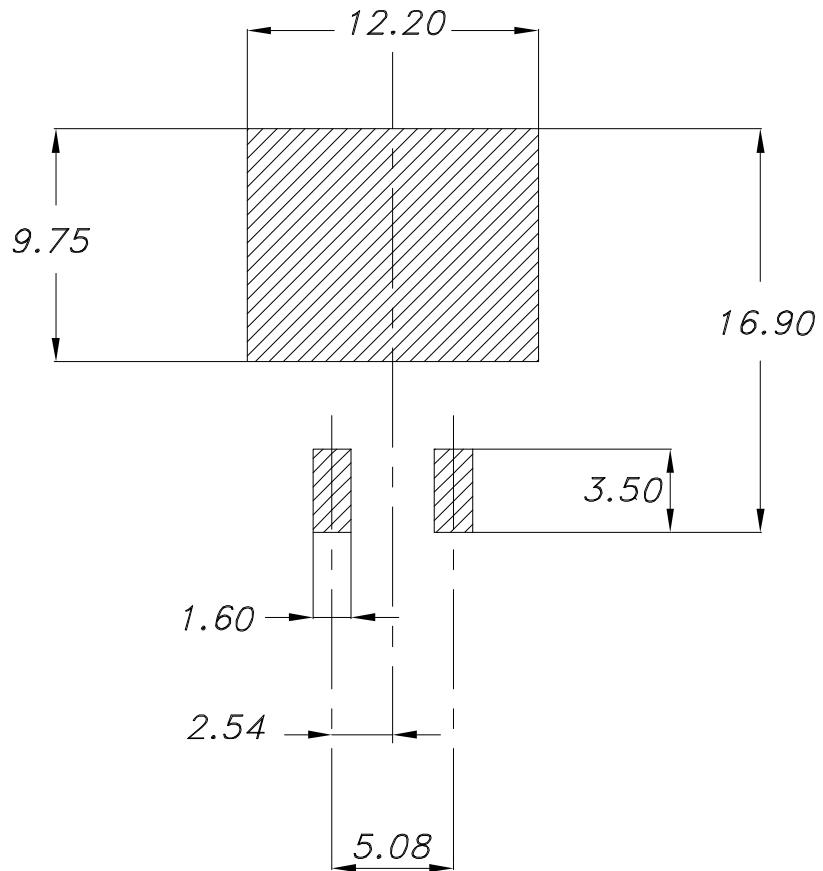


0079457\_26

**Table 7.** D<sup>2</sup>PAK (TO-263) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.30	8.50	8.70
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

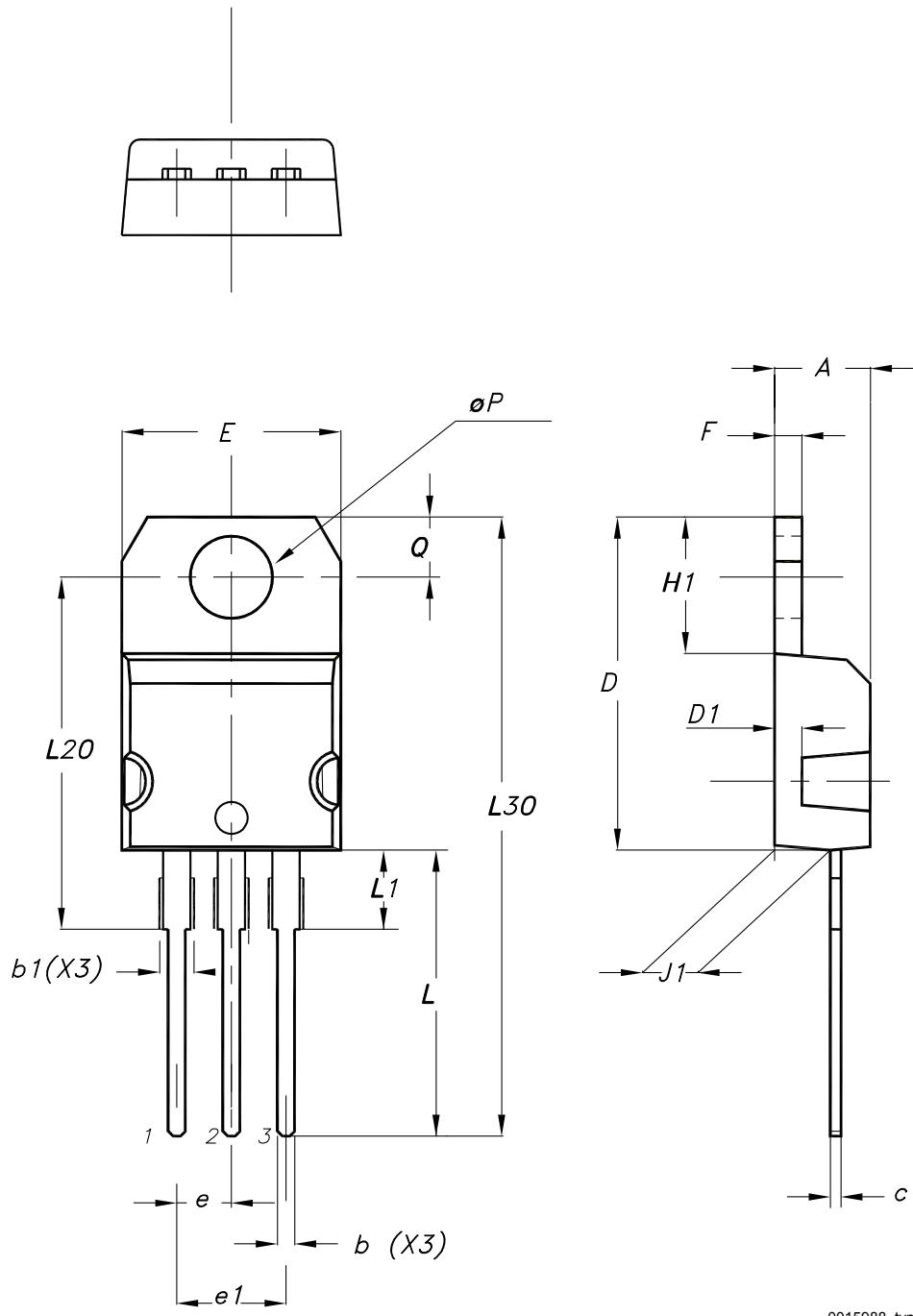
**Figure 20. D<sup>2</sup>PAK (TO-263) recommended footprint (dimensions are in mm)**



Footprint\_26

## 4.2 TO-220 type A package information

Figure 21. TO-220 type A package outline



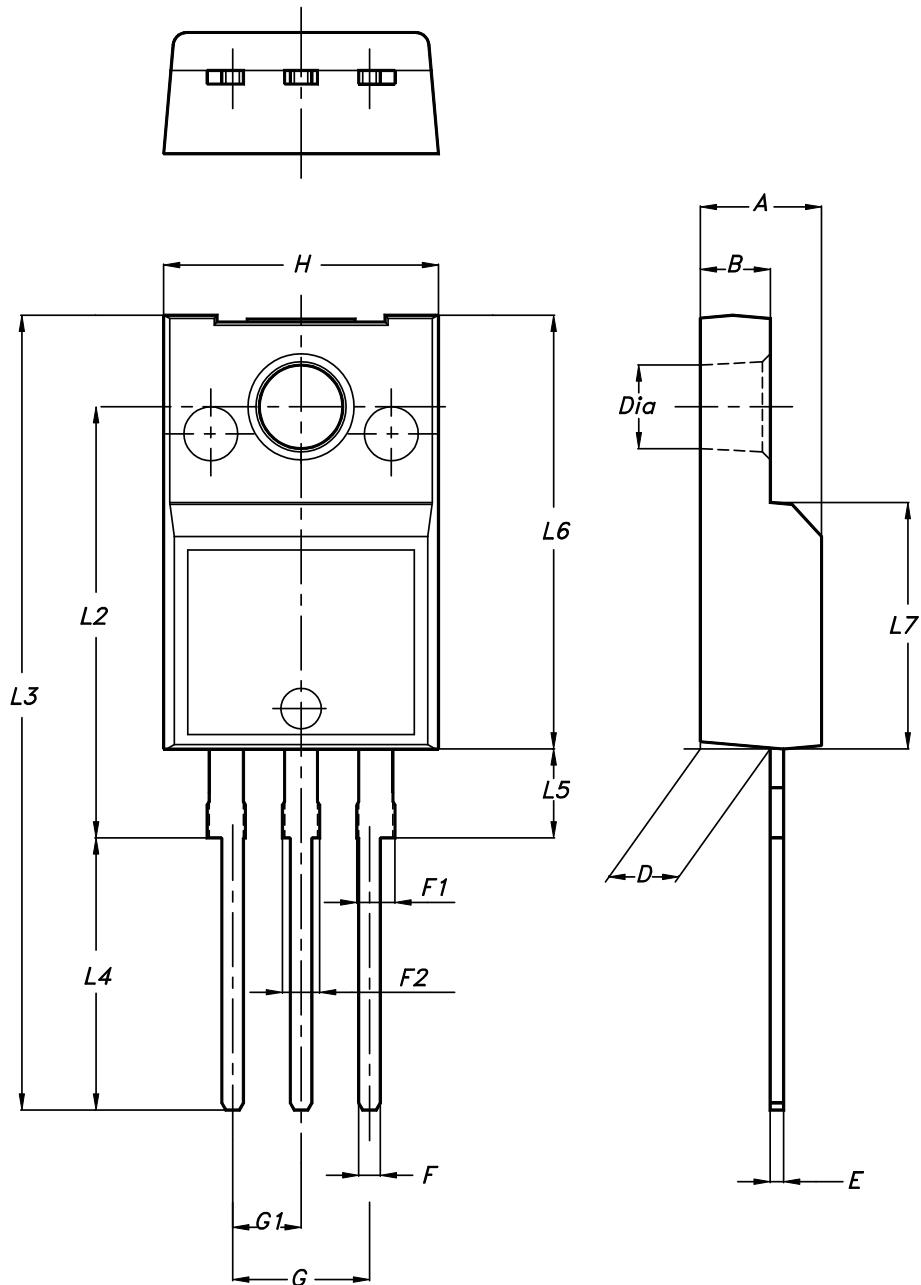
0015988\_typeA\_Rev\_23

**Table 8. TO-220 type A package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95
Slug flatness		0.03	0.10

#### 4.3 TO-220FP package information

Figure 22. TO-220FP package outline



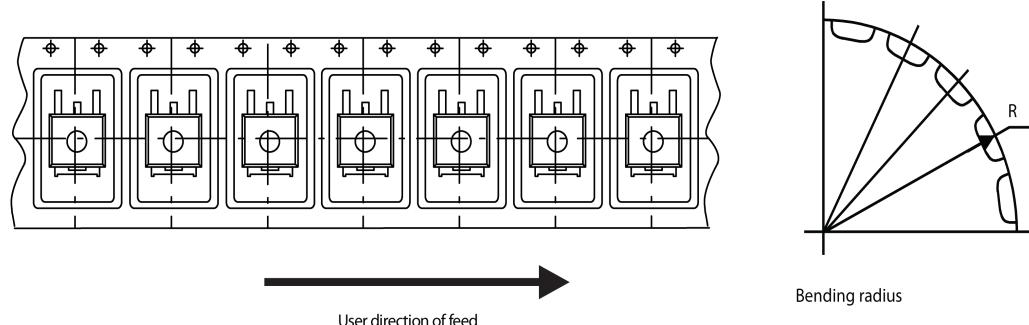
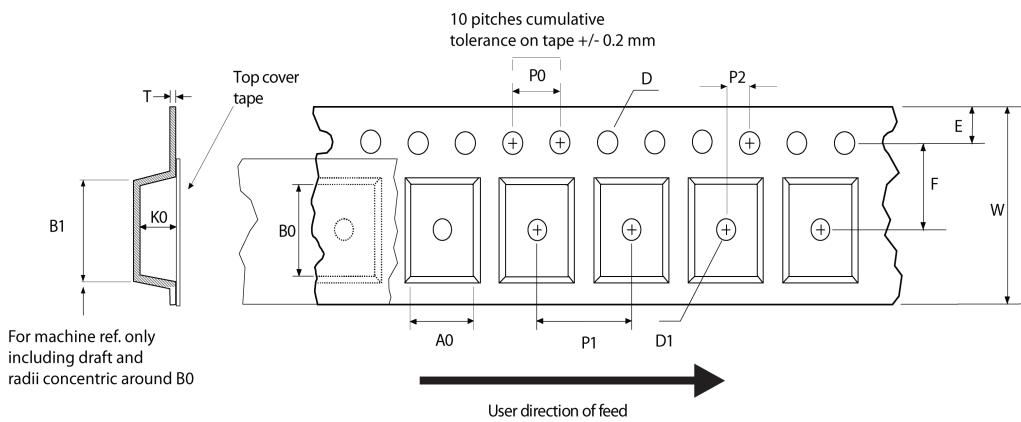
7012510\_Rev\_13\_B

**Table 9.** TO-220FP package mechanical data

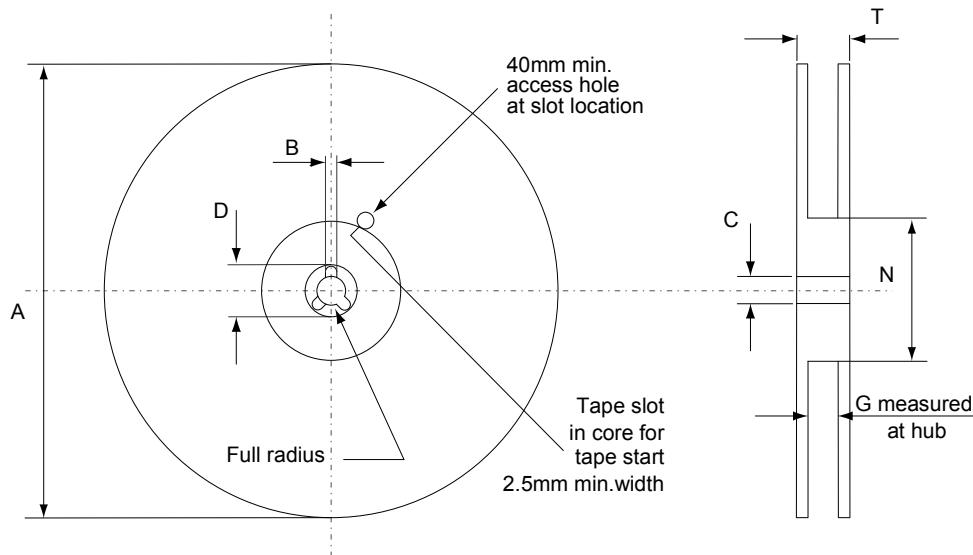
Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
E	0.45		0.70
F	0.75		1.00
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.20
G1	2.40		2.70
H	10.00		10.40
L2		16.00	
L3	28.60		30.60
L4	9.80		10.60
L5	2.90		3.60
L6	15.90		16.40
L7	9.00		9.30
Dia	3.00		3.20

## 4.4 D<sup>2</sup>PAK packing information

Figure 23. D<sup>2</sup>PAK tape outline



AM08852v1

**Figure 24. D<sup>2</sup>PAK reel outline**


AM06038v1

**Table 10. D<sup>2</sup>PAK tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

## 5 Ordering information

**Table 11. Order codes**

Order codes	Marking	Package	Packing
STB12NM50T4	B12NM50	D <sup>2</sup> PAK	Tape and reel
STP12NM50	P12NM50	TO-220	Tube
STP12NM50FP	P12NM50FP	TO-220FP	Tube

## Revision history

**Table 12. Document revision history**

Date	Revision	Changes
14-Mar-2004	8	Preliminary version
15-Feb-2006	9	New voltage value on first page at $t_{jmax}$ .
05-Apr-2006	10	Inserted ecopack indication
27-Jul-2006	11	New template, no content change
22-Oct-2020	12	The part number STB12NM50-1 have been moved to a separate datasheet and the document has been updated accordingly. Updated cover page. Updated <a href="#">Section 1 Electrical ratings</a> and <a href="#">Section 2 Electrical characteristics</a> . Added <a href="#">Section 5 Ordering information</a> . Minor text changes.

## Contents

<b>1</b>	<b>Electrical ratings</b>	<b>2</b>
<b>2</b>	<b>Electrical characteristics</b>	<b>3</b>
<b>2.1</b>	Electrical characteristics (curves)	5
<b>3</b>	<b>Test circuits</b>	<b>7</b>
<b>4</b>	<b>Package information</b>	<b>8</b>
<b>4.1</b>	D <sup>2</sup> PAK (TO-263) type A package information	8
<b>4.2</b>	TO-220 type A package information	11
<b>4.3</b>	TO-220FP package information	13
<b>4.4</b>	D <sup>2</sup> PAK packing information	15
<b>5</b>	<b>Ordering information</b>	<b>17</b>
	<b>Revision history</b>	<b>18</b>



**IMPORTANT NOTICE – PLEASE READ CAREFULLY**

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, please refer to [www.st.com/trademarks](http://www.st.com/trademarks). All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2020 STMicroelectronics – All rights reserved